Product / Package Information

Package	LCC_V
Body Size (mm)	9 X 9 X 4
Lead Count	14
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Combo Lid

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
	Nickel Plating						
Nickel & its alloys	Nickel	7440-02-0	2.17 E-03	1.7	17400	0.19	1909
	Gold Plating						
Precious metals	Gold	7440-57-5	2.49E-05	0.02	200	0.00	22
	Base						
Iron & its alloys	Iron	7439-89-6	6.82E-02	54.65	546455	5.99	59939
Iron & its alloys	Nickel	7440-02-0	4.74E-02	38.01	380051	4.17	41687
Iron & its alloys	Manganese	7439-96-5	5.77E-04	0.46	4627	0.05	508
Iron & its alloys	Silicon	7440-21-3	2.03E-04	0.16	1623	0.02	178
Iron & its alloys	Aluminum	7429-90-5	3.04E-05	0.02	244	0.00	27
	Solder Preform						
Precious metals	Gold	7440-57-5	4.79E-03	3.84	38368	0.42	4208
Tin & its alloys	Tin	7440-31-5	1.38E-03	1.10	11032	0.12	1210
Subtotal			1.25 E-01	100.00	1000000	10.97	109687

VMP Package

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
	Ceramics						
Ceramics	Aluminum oxide	1344-28-1	8.23 E-01	90.50	905000	72.34	723382
Ceramics	Chromium oxide	1308-38-9	3.55 E-02	3.90	39000	3.12	31173
Ceramics	Silicon Dioxide	7631-86-9	3.18 E-02	3.50	35000	2.80	27976
Ceramics	Titanium dioxide	13463-67-7	9.09 E-03	1.00	10000	0.80	7993
Ceramics	Calcium oxide	1305-78-8	5.45 E-03	0.60	6000	0.48	4796
Ceramics	Magnesium oxide	1309-48-4	4.55 E-03	0.50	5000	0.40	3997
Subtotal			**9.09 E-01**	**100.00**	**1000000**	**79.93**	**799317**
	Metallization						
Other inorganic materials	Tungsten	7440-33-7	5.05 E-02	75.01	750100	4.44	44412
Other inorganic materials	Molybdenum	7439-98-7	1.29 E-02	19.23	192300	1.14	11386
Other inorganic materials	Aluminum oxide	1344-28-1	3.45 E-03	5.13	51301	0.30	3037
Other inorganic materials	Silicon Dioxide	7631-86-9	2.09 E-04	0.31	3099	0.02	184
Other inorganic materials	Calcium oxide	1305-78-8	1.15 E-04	0.17	1700	0.01	101
Other inorganic materials	Silicic acid, zirconium (IV) salt	1344-21-4	7.41 E-05	0.11	1100	0.01	65
Other inorganic materials	Magnesium oxide	1309-48-4	2.69 E-05	0.04	399	0.00	24
Subtotal			**6.73 E-02**	**100.0**	**1000000**	**5.92**	**59209**
	Nickel Plating						
Nickel & its alloys	Nickel	7440-02-0	3.63 E-03	85.00	849992	0.32	3191
Other inorganic materials	Cobalt	7440-48-4	6.40 E-04	15.00	150008	0.06	563
Subtotal			**4.27 E-03**	**100.00**	**1000000**	**0.38**	**3754**
	Gold Plating						
Precious metals	Gold	7440-57-5	1.26 E-03	100.00	1000000	0.11	1109
Subtotal			9.82 E-01			86.34	863389

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum	7429-90-5	2.52 E-03	100.0	1000000	0.22	2216

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.53 E-02	100.0	1000000	2.22	22212

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Polymer	Polymer	Proprietary	2.84 E-03	100.00	1000000	0.25	2497

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.14 E+00**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES